

3.5x2.8 mm SMD CHIP LED LAMP

KA-3528SURCK

HYPER RED

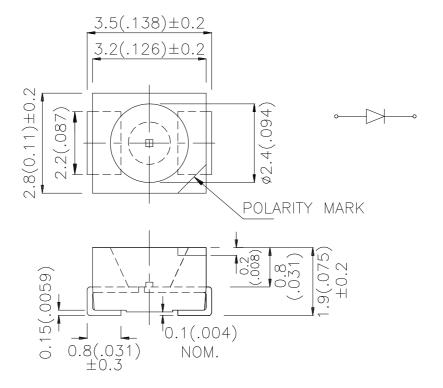
Features

- SINGLE COLOR.
- SUITABLE FOR ALL SMT ASSEMBLY AND SOLDER PROCESS.
- AVAILABLE ON TAPE AND REEL.
- IDEAL FOR BACKLIGHTING.
- PACKAGE: 1500PCS / REEL.
- •RoHS COMPLIANT.

Description

The Hyper Red source color devices are made with DH InGaAIP on GaAs substrate Light Emitting Diode.

Package Dimensions



Notes

- All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- 3. Specifications are subject to change without notice.

SPEC NO: DSAB4028 REV NO: V.8 DATE: MAR/16/2005 PAGE: 1 OF 4
APPROVED: J. Lu CHECKED: Allen Liu DRAWN: W.J.ZHU

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Selection Guide

Part No.	Dice	Lens Type	lv (mcd) @ 20mA		Viewing Angle
		,	Min.	Тур.	201/2
KA-3528SURCK	HYPER RED (InGaAIP)	WATER CLEAR	70	200	120°

Electrical / Optical Characteristics at Ta=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Hyper Red	650		nm	I _F =20mA	
λD	Dominant Wavelength	Hyper Red	635		nm	I _F =20mA	
Δλ1/2	Spectral Line Half-width	Hyper Red	28		nm	I _F =20mA	
С	Capacitance	Hyper Red	35		pF	V _F =0V;f=1MHz	
V _F	Forward Voltage	Hyper Red	1.95	2.5	V	I _F =20mA	
I _R	Reverse Current	Hyper Red		10	uA	V _R = 5V	

Absolute Maximum Ratings at Ta=25°C

Parameter	Hyper Red	Units
Power dissipation	75	mW
DC Forward Current	30	mA
Peak Forward Current [1]	185	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

SPEC NO: DSAB4028 **REV NO: V.8** DATE: MAR/16/2005 PAGE: 2 OF 4 DRAWN: W.J.ZHU

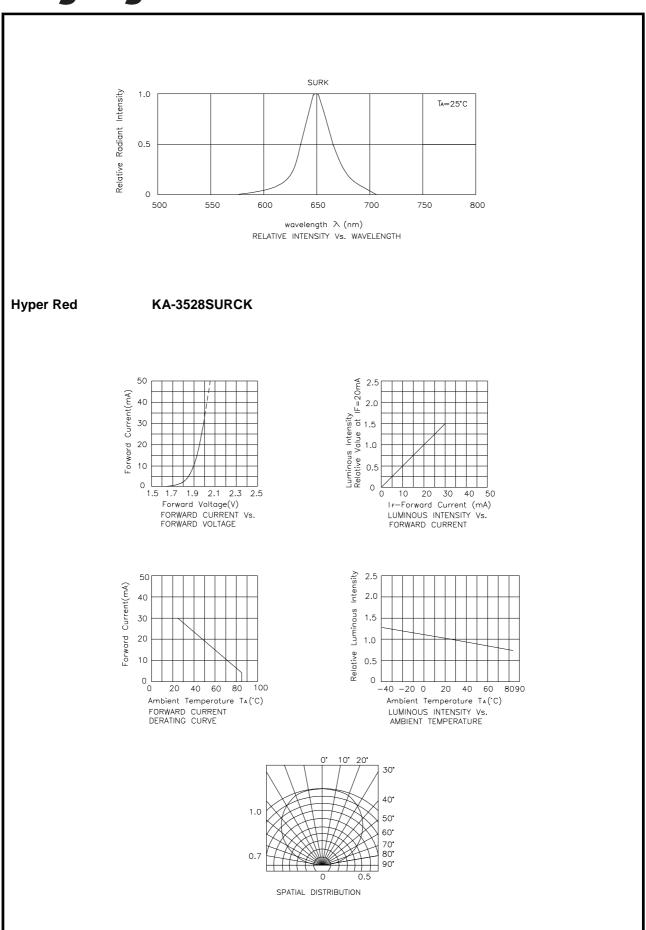
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Note: 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

^{1. 1/10} Duty Cycle, 0.1ms Pulse Width.

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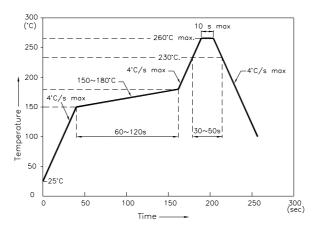
SPEC NO: DSAB4028 **REV NO: V.8 DATE: MAR/16/2005** PAGE: 3 OF 4 **CHECKED: Allen Liu** DRAWN: W.J.ZHU

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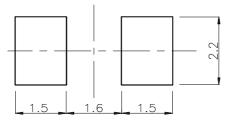
Reflow Soldering Profile For Lead-free SMT Process.



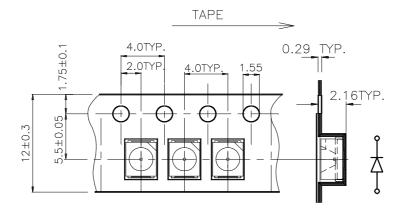
- NOTES: 1.We recommend the reflow temperature 245°C(+/-5°C). The temperature should be limited to 260°C. maximum soldering temperature should be limited to 260°C.
 - 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.
 - 3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern

(Units: mm)



Tape Specifications (Units: mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

- 1. Wavelength: +/-1nm
- 2. Luminous Intensity: +/-15%
- 3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

SPEC NO: DSAB4028 **REV NO: V.8 DATE: MAR/16/2005** PAGE: 4 OF 4 APPROVED: J. Lu **CHECKED: Allen Liu** DRAWN: W.J.ZHU